

## ABSTRACT

A wire bonder (900) with a rigid pedestal (902) having resilient inserts (920). A package (904) placed on the pedestal (902) contains an electrical device (906). The bond pads on the electrical device (906) are electrically connected to bond pads on the package (904) by a series  
5 of bond wires (908) through use of a well know bonding process. A vacuum source holds the package (904) against the pedestal (902) deforming the resilient strips (920) located in the rigid member (902) of the pedestal and ensuring good contact between the ground pads of the package (904) and conductive resilient members (920). The resilient members (920) are conductive and electrically connect the package grounds to a system ground (922).

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